

**TRANSMITTAL OF FORMAL DRAWINGS**

Docket No.

SLA0499

Re Application Of: Wei Pan, David R. Evans and Sheng Teng Hsu

Serial No.	Filing Date	Batch No.	Examiner	Art Unit
09/978,434	10/16/2001		Timothy H. Meeks	1762

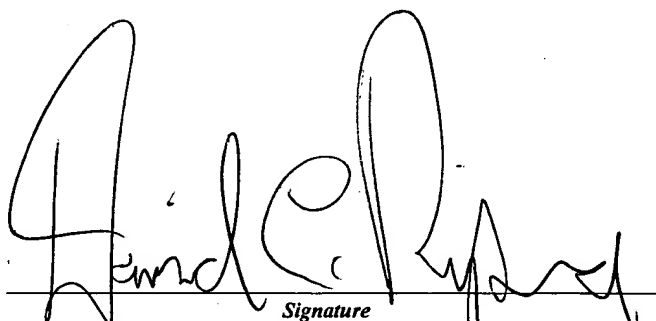
Invention: **Method of Controlling the Initial Growth of CVD Copper Films by Surface Treatment of Barrier Metals Films**

Address to:
Assistant Commissioner for Patents
Washington, D.C. 20231

Transmitted herewith are:

2 sheets of formal drawing(s) for this application.

Each sheet of drawing indicates the identifying indicia suggested in 37 CFR Section 1.84(c) on the reverse side of the drawing.


Signature
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Dated: December 5, 2003

I certify that this document and attached formal drawings are being deposited on December 5 2003 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.


Signature of Person Mailing Correspondence

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